

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6954612

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WEN DAR LIU	08/03/2021
YI-CHIA LEE	08/03/2021
RECEIVING PARTY DATA	
Name:	VERSUM MATERIALS US, LLC
Street Address:	8555 SOUTH RIVER PARKWAY
Internal Address:	PATENT DEPT.
City:	TEMPE
State/Country:	ARIZONA
Postal Code:	85284
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17416328
CORRESPONDENCE DATA	
Fax Number:	(610)862-9626
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4842465768
Email:	VersumPatents@emdgroup.com
Correspondent Name:	LISA HOFFMANN
Address Line 1:	7350 TILGHMAN STREET, SUITE 104
Address Line 2:	PATENT DEPT.
Address Line 4:	ALLENTOWN, PENNSYLVANIA 18106-9000
ATTORNEY DOCKET NUMBER:	09335 US-PCT
NAME OF SUBMITTER:	WILLIAM T. SLAVEN IV
SIGNATURE:	/William T. Slaven IV/
DATE SIGNED:	10/06/2021
Total Attachments: 2	
source=09335-us-pct-assignment#page1.tif	
source=09335-us-pct-assignment#page2.tif	

PATENT ASSIGNMENT

WHEREAS, I/we, Wen Dar Liu and Yi-Chia Lee, have made an invention, which invention is described in an application for Letters Patent titled "Hafnium Oxide Corrosion Inhibitor," filed in the United States Patent and Trademark Office, assigned Patent Application No.: 17/416,328 and accorded Filing Date of 18 June 2021; and

WHEREAS, Versum Materials US, LLC, of 8555 South River Parkway, Tempe, Arizona 85284, a limited liability company organized and existing under the laws of Delaware (hereinafter "Company") is desirous of acquiring, and entitled by agreement, contract, or operation by law, to acquire the entire right, title and interest in and to the invention and in and to the application and any Letters Patent that may be granted therefor;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned have sold, assigned and transferred, and do hereby sell, assign and transfer unto Company, its lawful successors and assigns, the full, exclusive and worldwide right to the invention and the entire right, title and interest in, to and under the application and any and all Letters Patent(s) that may be granted on the application, any and all priority applications and Letters Patent thereof, and any and all applications and Letters Patent claiming priority to the application, including any and all divisions or continuations thereof, any and all renewals, substitutes, reissues, reexaminations and extensions thereof, in the United States of America, in the territorial possessions of the United States of America, and equivalents thereto in any country foreign to the United States of America, including full right to claim for any such applications all benefits and priority rights under any applicable convention, the same to be held and enjoyed by Company, its lawful successors and assigns as fully and entirely as the same would have been held by the undersigned had this assignment not been made.

The undersigned hereby authorize and request the Commissioner of Patent and Trademarks of the United States of America and respective Patent Office officials in any country foreign to the United States of America to issue said Letters Patent to Company as the assignee of our entire right, title and interest in, to and under the same, and we hereby further authorize Company to apply for Letters Patent in the undersigned name(s) or in Company's name, as Company in its sole discretion sees fit, utilizing any benefits which may exist under any International Agreement, in any country.

The undersigned hereby agree for ourselves and for our heirs, executors and administrators, to execute any lawful document and to testify as to any material fact or thing which Company, its lawful successors, assigns and legal representatives may deem necessary in order to secure unto itself, its lawful successors and assigns the full right, title and interest in and to, and the full enjoyment of, the invention or any part thereof, the applications and any and all Letters Patent, the same to be done without any further consideration.

The undersigned hereby warrant and represent that I/we have not entered, nor will enter, into any assignment, contract, or understanding in conflict herewith.

IN TESTIMONY WHEREOF, I hereby set my hand this 3rd day of August, 2021.

Inventor Signature: Wen Dar Liu
 Inventor Name: **Wen Dar Liu**

Witness 1:

I attest that on this day **Wen Dar Liu** did sign above in my presence of his/her own free will.

Witness Signature: Aron Chen

Witness Name: Aron Chen

Date: 3rd August 2021

Witness 2:

I attest that on this day **Wen Dar Liu** did sign above in my presence of his/her own free will.

Witness Signature: Sheng Wen

Witness Name: Sheng Wen

Date: 3rd August 2021

IN TESTIMONY WHEREOF, I hereby set my hand this 3rd day of August, 2021.

Inventor Signature: Yi Chia Lee
 Inventor Name: **Yi-Chia Lee**

Witness 1:

I attest that on this day **Yi-Chia Lee** did sign above in my presence of his/her own free will.

Witness Signature: Aron Chen

Witness Name: Aron Chen

Date: 3rd August 2021

Witness 2:

I attest that on this day **Yi-Chia Lee** did sign above in my presence of his/her own free will.

Witness Signature: Sheng Wen

Witness Name: Sheng Wen

Date: 3rd August 2021